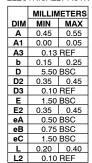


UDFN18, 5.5x1.5, 0.5P/0.75P CASE 517CP **ISSUE A**

DATE 07 FEB 2013

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS.
- DIMENSION & APPLIES TO PLATED
 TERMINAL AND IS MEASURED BETWEEN
- 0.10 AND 0.20 MM FROM TERMINAL TIP.
 COPLANARITY APPLIES TO THE EXPOSED
- PAD AS WELL AS THE TERMINAL EXPOSED ENDS OF TERMINALS ARE ELECTRICALLY ACTIVE.



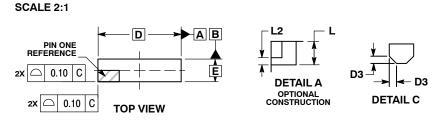
GENERIC MARKING DIAGRAM*

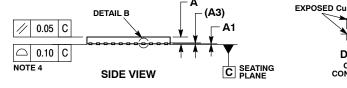


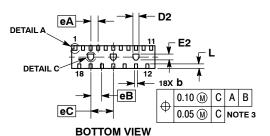
XXXX = Specific Device Code Μ = Date Code

= Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking.









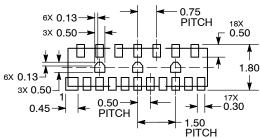
END VIEW

DETAIL B

OPTIONAL CONSTRUCTION

MOLD CMPD

RECOMMENDED SOLDERING FOOTPRINT*



NOTE: CENTER PADS OPTIONAL

DIMENSION: MILLIMETERS

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^{*}For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.